

ABSTRACT

A multi-layered adhesive sheet 100, includes: a substrate film 106, an adhesive layer 103 formed by coating an adhesive having a specific composition onto this substrate film 106, and a die attachment film 105 laminated on the adhesive layer 103. The multi-layered adhesive sheet 100 employing an adhesive having this specific composition has superior retention of die chip 108 during the dicing of silicon wafer 101, allows the die attachment film 105 and adhesive layer 103 to be easily peeled apart during a pick-up operation of the die chip 108, and prevents poor adhesion during the bonding of die chip 108 to lead frame 111.